IPC Standard Released on Application of Solder Paste

Written by Chelsey Drysdale Wednesday, 08 August 2012 15:33 -

BANNOCKBURN, IL – The first **IPC** standard that originated outside the US, IPC-7527, *Requir* ements for Solder Paste Printing

, is the first standard developed that focuses on the application of solder paste.

Recently released, IPC-7527 was the brainchild of **Task Group Nordic**, IPC's volunteer standards development group in Scandinavia.

The new standard will help companies assess and improve their solder paste printing processes, says IPC.

IPC-7527 covers many aspects of solder paste application, from initial placement on the board through production and testing. The standard is a reference guide with more than 50 photos in the 15-page document.

It provides requirements for what the printed solder paste should look like and how far off centers can be before they're considered defects. It covers everything from basic squeegees to jet dispensers and needle dispensers to closed print heads.

In addition, IPC-7527 provides information on automated paste inspection using either cameras or lasers.

The standard also brings out common problems, like solder with rooftops or saddle shapes instead of brick forms, and it suggests solutions to fix those issues.

For more information, visit www.ipc.org/7527.